

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | |
|--|--------------------------------|---------------|----------------|---------------------|------------|---------------|------------|--------------|------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Weng Foong Yap</td> <td>07/06/2012</td> </tr> <tr> <td>Lai Cheng Law</td> <td>07/06/2012</td> </tr> <tr> <td>Boh Kid Wong</td> <td>07/06/2012</td> </tr> </tbody> </table> | | Name | Execution Date | Weng Foong Yap | 07/06/2012 | Lai Cheng Law | 07/06/2012 | Boh Kid Wong | 07/06/2012 |
| Name | Execution Date | | | | | | | | |
| Weng Foong Yap | 07/06/2012 | | | | | | | | |
| Lai Cheng Law | 07/06/2012 | | | | | | | | |
| Boh Kid Wong | 07/06/2012 | | | | | | | | |
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| State/Country: | TEXAS | | | | | | | | |
| Postal Code: | 78735 | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13544430</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 13544430 | | | | |
| Property Type | Number | | | | | | | | |
| Application Number: | 13544430 | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | |
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| ATTORNEY DOCKET NUMBER: | MT11854ZK | | | | | | | | |
| NAME OF SUBMITTER: | Ryan S. Davidson | | | | | | | | |

CH \$40.00 13544430

Total Attachments: 4

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ASSIGNMENT OF U.S. PATENT APPLICATION

This is an assignment of patent rights between the inventor(s)

Weng Foong Yap

Lai Cheng Law

Boh Kid Wong

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **Weng Foong Yap, Lai Cheng Law, and Boh Kid Wong**, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto **FREESCALE SEMICONDUCTOR, INC.** a corporation of the State of Delaware, having its principal office in Austin, Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **DEVICE PACKAGE WITH RIGID INTERCONNECT STRUCTURE CONNECTING DIE AND SUBSTRATE AND METHOD THEREOF** (Docket No. **MT11854ZK**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto **FREESCALE SEMICONDUCTOR, INC.**, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefore in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize **FREESCALE SEMICONDUCTOR, INC.** to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to **FREESCALE SEMICONDUCTOR, INC.**, for the sole use and benefit of **FREESCALE SEMICONDUCTOR, INC.**, its successors, assigns and legal representatives,

to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to **FREESCALE SEMICONDUCTOR, INC.**

We agree that, when requested, we will, without charge to **FREESCALE SEMICONDUCTOR, INC.**, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in **FREESCALE SEMICONDUCTOR, INC.**, its successors, assigns and legal representatives or nominees.

We covenant with **FREESCALE SEMICONDUCTOR, INC.**, its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

This assignment is executed on the date(s) of which the Inventors have signed.

Inventors:



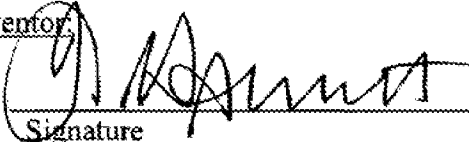
6 July 2012

Weng Foong Yap

Date:

Witnesses for First Inventor:

First Witness:

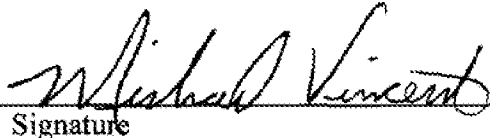

Signature

7/6/2012
Date

Tom SPEIGHT
Full Name (printed)

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Address (Street, City, State, Zip)

Second Witness:


Signature

7/6/2012
Date

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Lai Cheng

6 July 2012

Lai Cheng Law

Date

Witnesses for Second Inventor:

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[Signature]

6 July 2012

Signature

Date

Teh Seah Hian

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Second Witness:

[Signature]

6 July 2012

Signature

Date

Foong Chee Seng

Full Name (printed)

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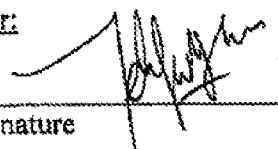
6 July 2012

Boh Kid Wong

Date

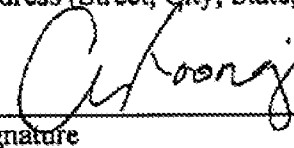
Witnesses for Third Inventor:

First Witness:


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 Full Name (printed) _____

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Second Witness:


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 Full Name (printed) _____

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